NEWS BULLETIN

NEXX Systems, Inc.
900 Middlesex Turnpike, Bldg. 6
Billerica, MA 01821-3929

For immediate release

For further information:

Cristina Chu
Investor Relations
978-932-2096

NEXX Systems Ships 50th Stratus Electrochemical Deposition System to a Taiwan Foundry

Billerica, MA – July 1, 2010 – NEXX Systems, a leading provider of processing equipment for advanced wafer-level packaging applications, today announced the shipment of its 50th Stratus electrochemical deposition system, to be installed at a Taiwanese foundry, which already has other NEXX tools helping them deliver smaller, faster and smarter components for electronics. The Stratus S300 tools are used for production of multiple advanced packaging technologies enabling the foundry to deliver high volume, high performance, and low cost of ownership for next generation bumping solutions to its customers as well as to enable further collaboration with NEXX on development of future advanced packaging applications.

About NEXX Stratus/Apollo Product Families: Stratus provides industry-leading yield at what we believe is the lowest CoO for pattern plating and TSV applications. NEXX Systems' AquaTorr™, an advanced prewet system, enables high aspect ratio, void-free copper fill for TSVs. Innovative ShearPlate™ technology provides exceptional process with excellent across wafer uniformity and alloy composition.

The Apollo advanced sputter deposition system incorporates multi-wafer processing commonly used in cluster tools while avoiding the disadvantages of central handling. The Apollo, specifically designed for wafer level packaging offers faster, more economical PVD processing.

About NEXX: NEXX Systems brings exceptional technical expertise to the flip chip and advanced packaging markets. Our product lines provide the most efficient, yet affordable, systems of their kind: Apollo for multi-layer sputter deposition of metals, and Stratus for high throughput electro-deposition of metals. Additional information can be found at: *www.nexxsystems.com*.